



# **Thermal processes in metal nanosystems after short pulsed laser heating**

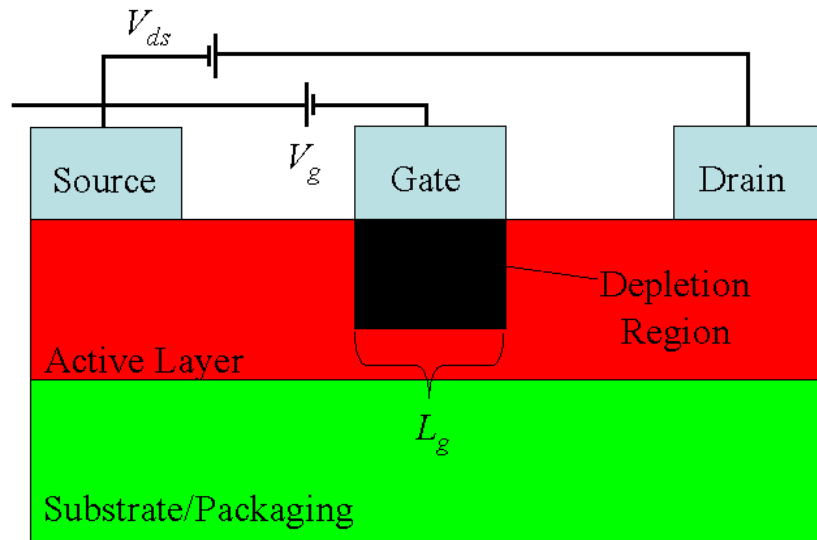
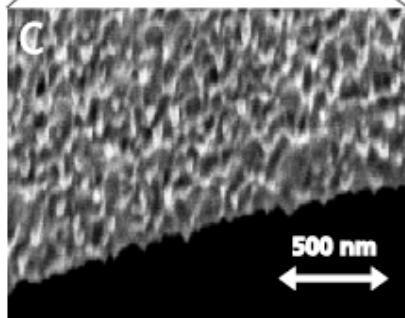
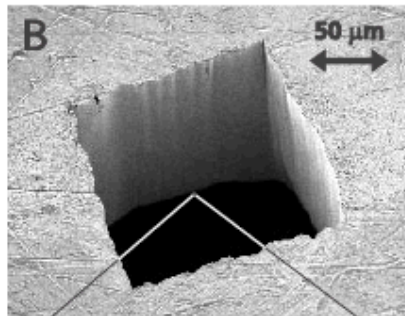
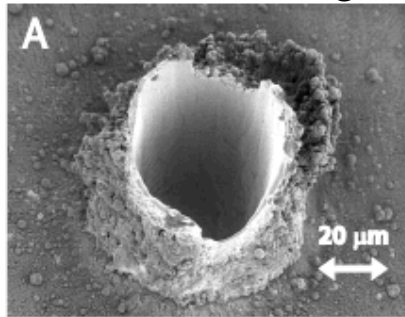
**CINT/LANL Seminar**

**Thursday, June 18, 2009**

**Patrick E. Hopkins, Justin R. Serrano, & Leslie M. Phinney  
Sandia National Laboratories, Albuquerque, NM**

# Thermal processes in metals

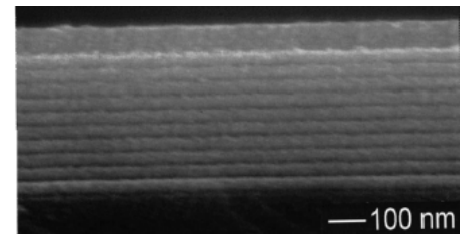
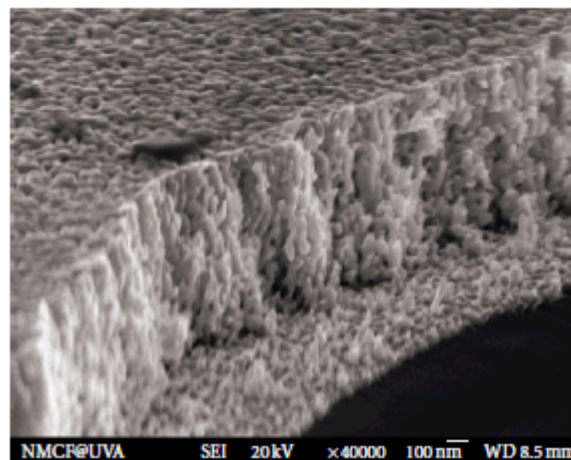
Laser machining and manufacturing



Heat generated at metal contacts in transistors

Multilayered systems – understanding interface conductance

Nanoporous metals



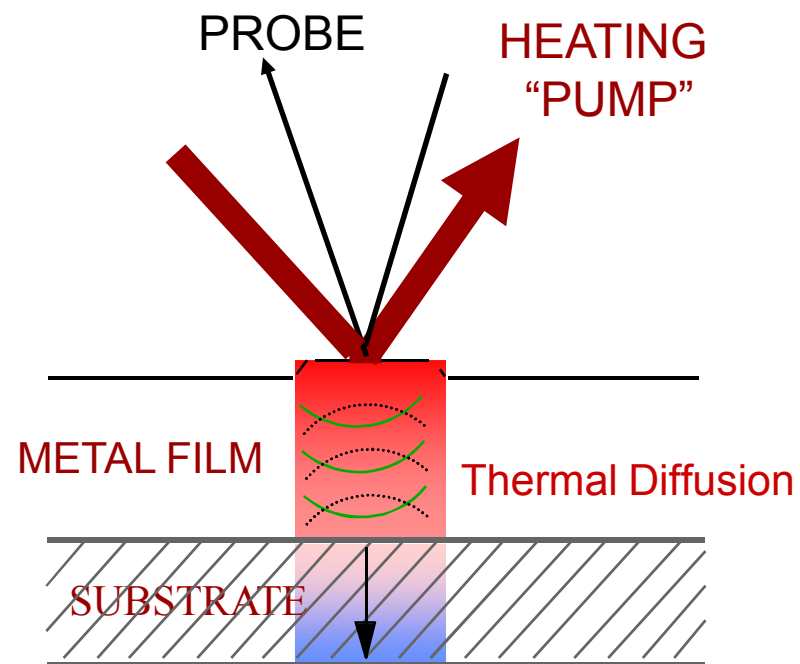
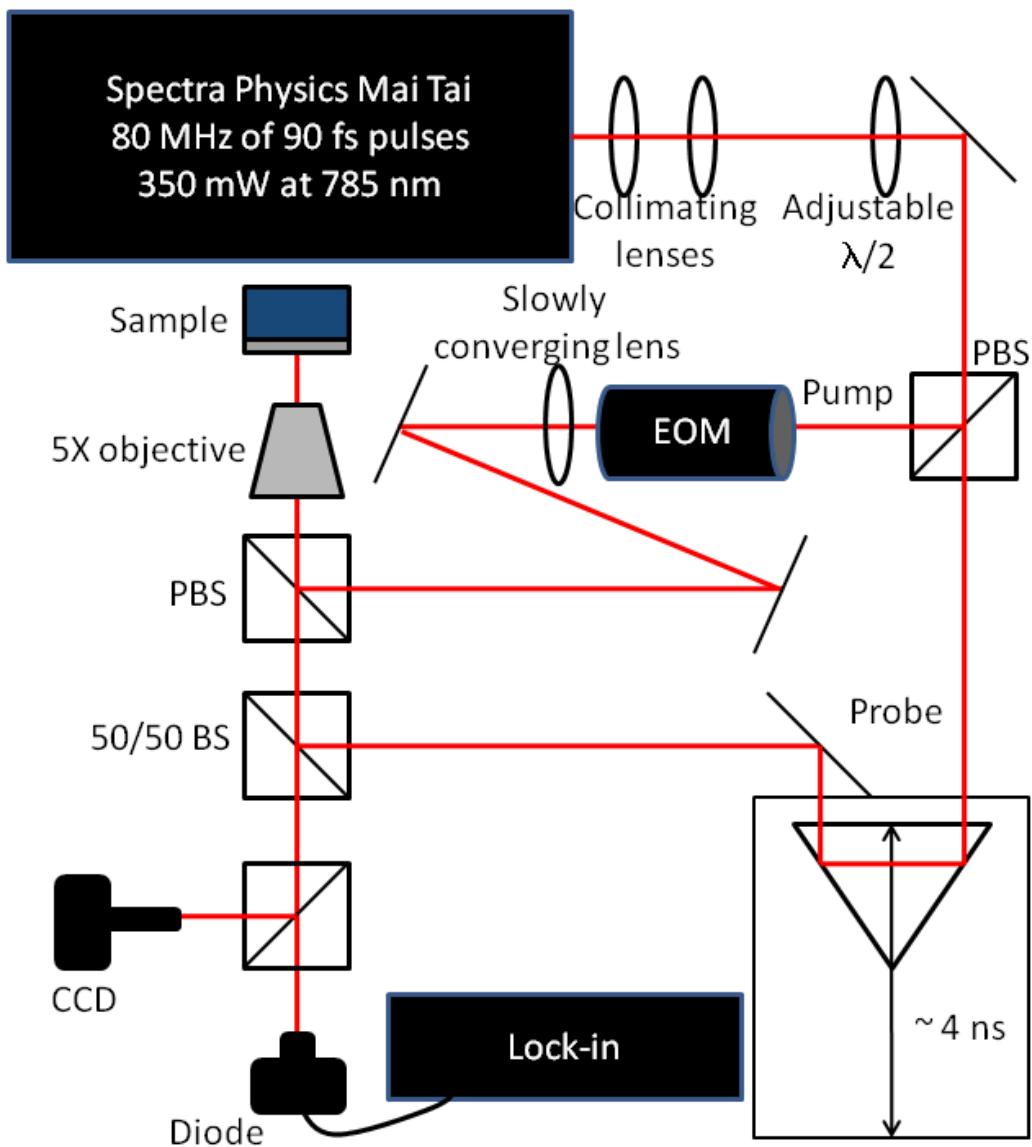
$$ZT = \frac{S^2 \sigma T}{k}$$



# Outline

- **The transient thermorefectance technique (TTR)**
  - Thermal conductivity measurements of metalized layers
  - Electron-phonon coupling factor measurements in metal films
  - Effects of interface scattering
- **Electron scattering in nanoporous metals**
- **Electron-phonon coupling enhancement due to d-band excitations**
  - Ballistic transport
  - Interface scattering

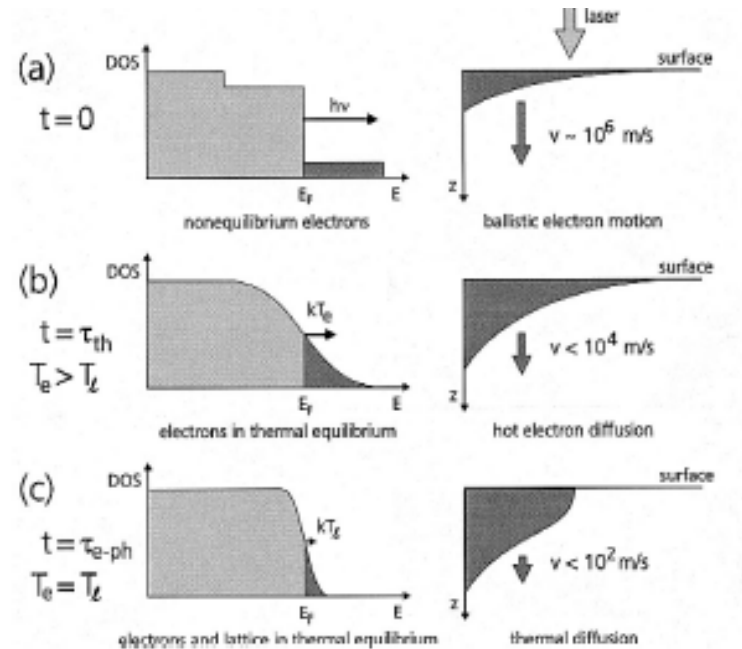
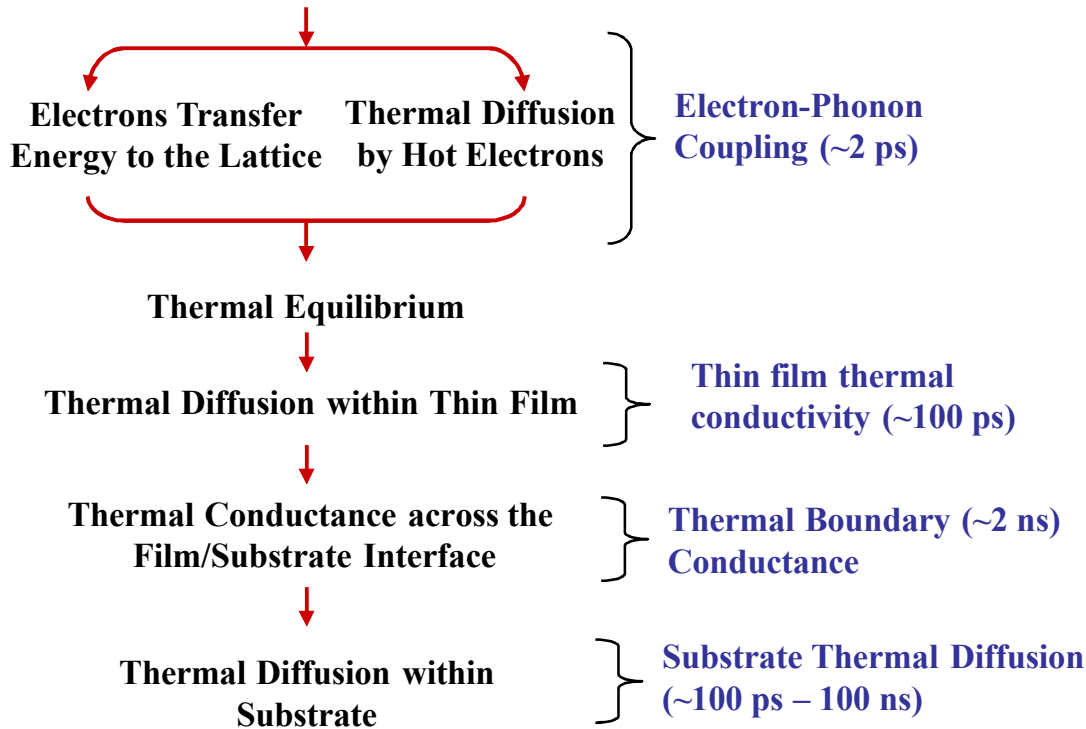
# TTR technique



# Thermal processes measured with the TTR technique

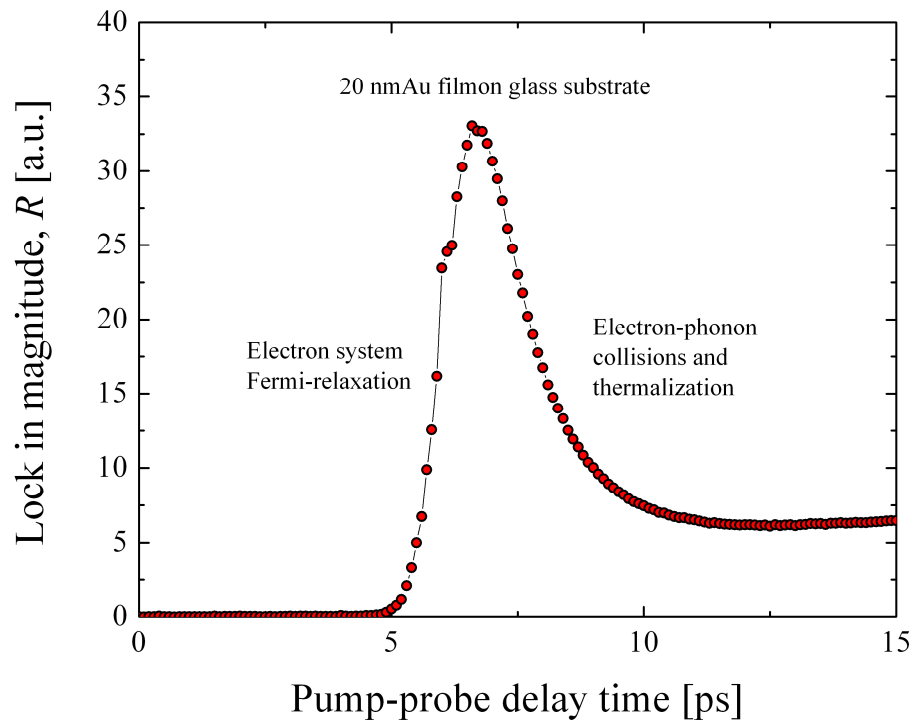
## Thermal processes in metal films

Free Electrons Absorb Laser Radiation

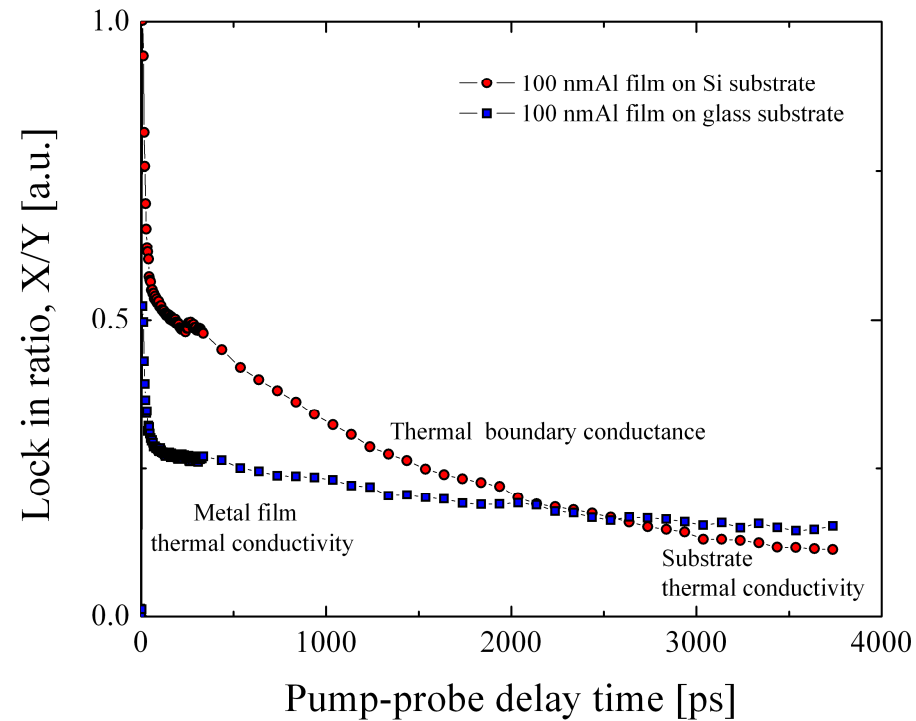


# TTR data

## Electron-phonon coupling



## Thermal diffusion





# Determining the thermal conductivity, $\Lambda$

REVIEW OF SCIENTIFIC INSTRUMENTS

VOLUME 75, NUMBER 12

DECEMBER 2004

## Analysis of heat flow in layered structures for time-domain thermorefectance

David G. Cahill<sup>a)</sup>

*Department of Materials Science and Engineering and Frederick Seitz Materials Research Laboratory,  
University of Illinois, Urbana, Illinois 61801*

REVIEW OF SCIENTIFIC INSTRUMENTS 79, 114902 (2008)

## Pulse accumulation, radial heat conduction, and anisotropic thermal conductivity in pump-probe transient thermorefectance

Aaron J. Schmidt,<sup>a)</sup> Xiaoyuan Chen, and Gang Chen

*Department of Mechanical Engineering, Massachusetts Institute of Technology, Cambridge,  
Massachusetts 02139-4307, USA*

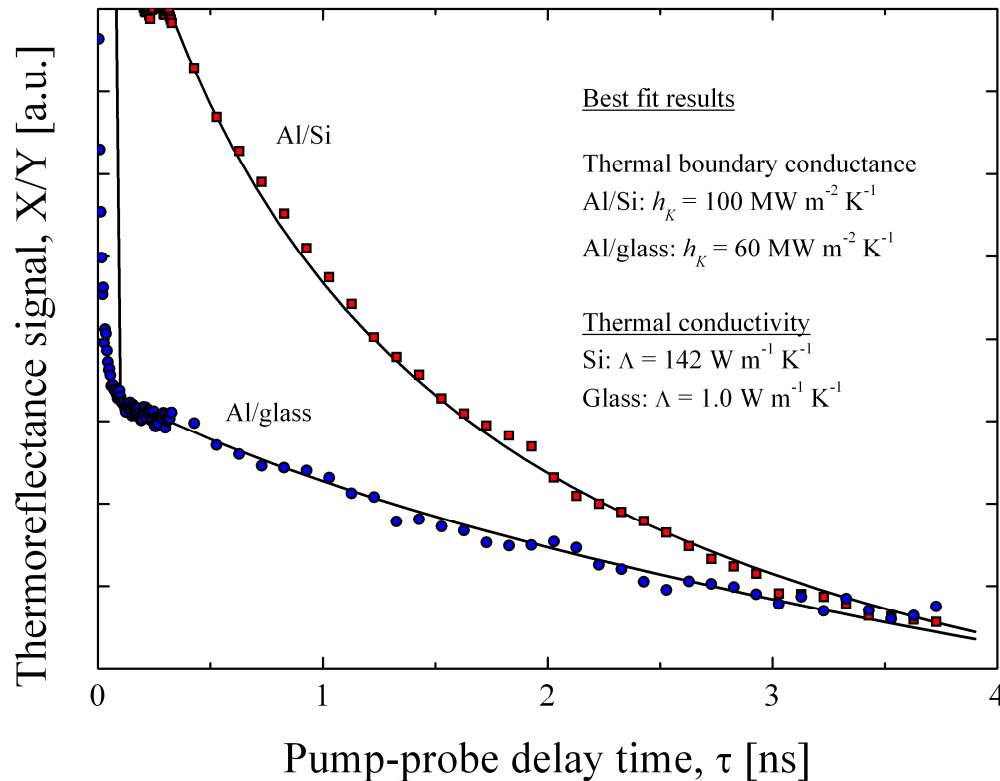
Utilize lock-in signals to  
deduce thermal diffusion  
phenomena

$$Z(\omega_0) = \frac{(2\pi)^2 \chi}{\omega_s^2} \sum_{M=-\infty}^{\infty} \theta(\omega_0 + M\omega_s) \exp[iM\omega_s \tau]$$

Must know analytical form of  
surface temperature rise

$$\theta(\omega) = \frac{A}{2\pi} \int_0^{\infty} F(k) \exp\left[\frac{-k^2(w_0^2 + w_1^2)}{8}\right] k dk$$

# Determining the thermal conductivity, $\Lambda$



$$\frac{X}{Y} = \frac{\text{Re}[Z(\omega_0)]}{\text{Im}[Z(\omega_0)]}$$

Extended to measure thermal conductivity of multilayer films

IMECE2009-12238

**EFFECTS OF THERMAL ANALYSIS ON THERMAL CONDUCTIVITY  
MEASUREMENTS IN PUMP-PROBE THERMOTREFLECTANCE TECHNIQUES**  
Patrick E. Hopkins\*, Justin R. Serrano, Leslie M. Phinney, Sean P. Kearney, Thomas W. Grasser

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Massachusetts Institute of Technology  
Cambridge, MA, USA 02139-4307

To be presented at  
**ASME IMECE** in  
November





# Determining the electron-phonon coupling factor, $G$

REVIEW OF SCIENTIFIC INSTRUMENTS 77, 084901 (2006)

## Signal analysis and characterization of experimental setup for the transient thermoreflectance technique

Robert J. Stevens<sup>a)</sup>

*Mechanical Engineering Department, Rochester Institute of Technology, Rochester, New York 14623*

Andrew N. Smith

*Department of Mechanical Engineering, United States Naval Academy, Annapolis, Maryland 21402*

Pamela M. Norris

*Department of Mechanical and Aerospace Engineering, University of Virginia, Charlottesville, Virginia 22904*

$$R = a\Delta T$$

Lock in magnitude is proportional to temperature rise through  $a$  (thermoreflectance coefficient)

$$\longrightarrow \Delta T$$

Temperature rise determined from thermal model

$$\searrow \phi$$

Pulse accumulation from lock in phase

Advantage: Do not need to know analytical form of  $\Delta T$

Disadvantage:  $R$  contains instrument noise where  $X/Y$  noise cancels out

# Determining the electron-phonon coupling factor, $G$

The two temperature model (TTM)

Energy stored in  $e$  system

Energy conducted through  $e$  system

Energy transferred from  $e$  system to  $p$  system

$$\gamma_e T_e \frac{\partial T_e}{\partial t} = \frac{\partial}{\partial z} \left( k_e(T_e, T_p) \frac{\partial T_e}{\partial z} \right) - G[T_e - T_p] + S(z, t)$$

Energy deposited into  $e$  system

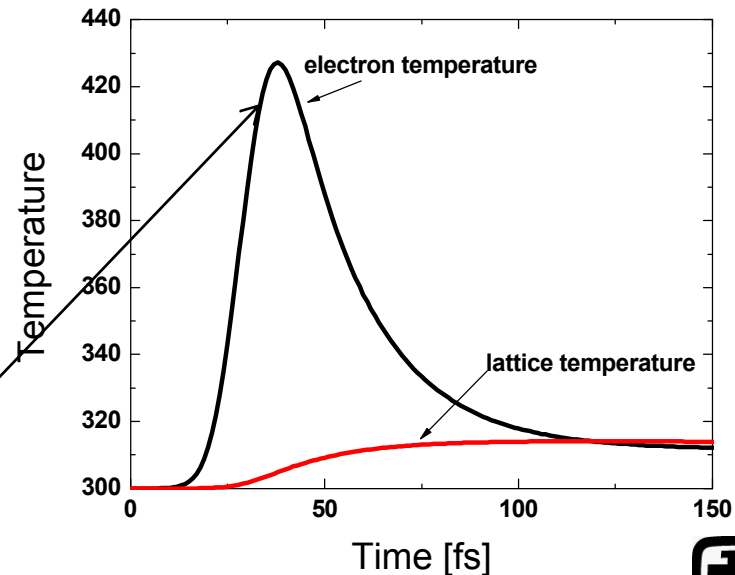
Electron-phonon coupling factor

$$C_p \frac{\partial T_p}{\partial t} = G[T_e - T_p]$$

Energy stored in  $p$  system

Energy gained by  $p$  system from  $e$  system

Note large change in temperature at early pump-probe time delays



# Determining the electron-phonon coupling factor, $G$

The thermorefectance coefficient

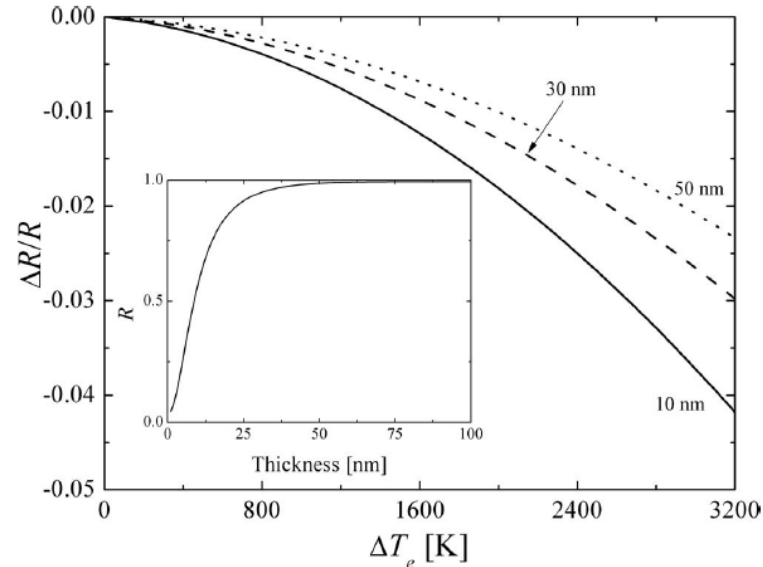
From TTM

$$\Delta T_e \text{ \& } \Delta T_p$$

$$R = a\Delta T_e + b\Delta T_p$$

Phase corrected data

Linear  
thermorefectance  
relation only valid  
when  $\Delta T < 150$  K



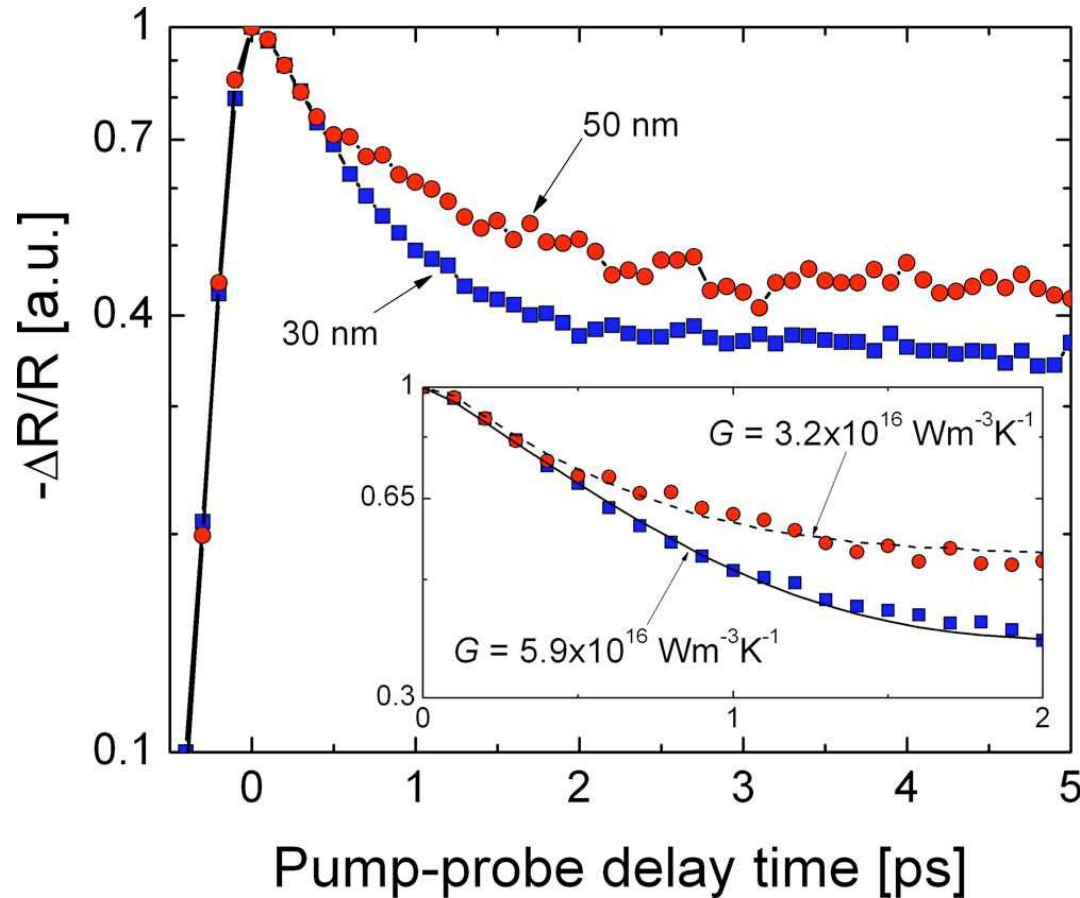
Consider Drude  
model

$$n = n_1 + in_2 = \sqrt{\epsilon_f} = \sqrt{1 - \frac{\omega_p^2}{\omega \left( \omega + \frac{i}{\tau} \right)}}$$

Nonlinear thermorefectance relation for free  
electron metals

$$R = f(\Delta T_e) + b\Delta T_p$$

# Determining the electron-phonon coupling factor, $G$



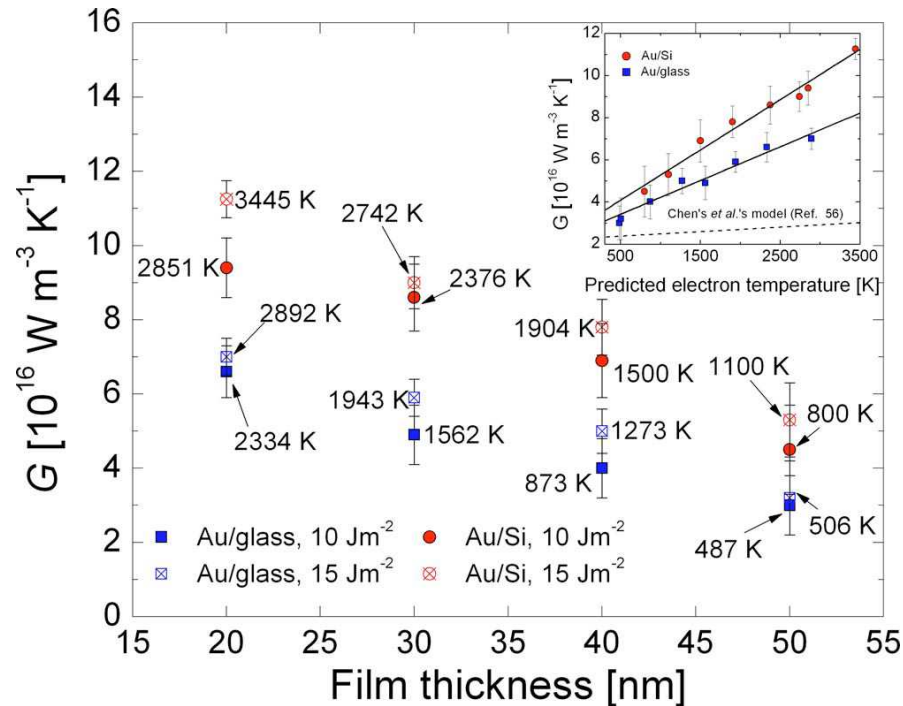
$G$  is a material property. For Au,  $G = 3 \times 10^{16} \text{ W m}^{-3} \text{ K}^{-1}$ .  
Measured  $G$  changes with film thickness. Why?



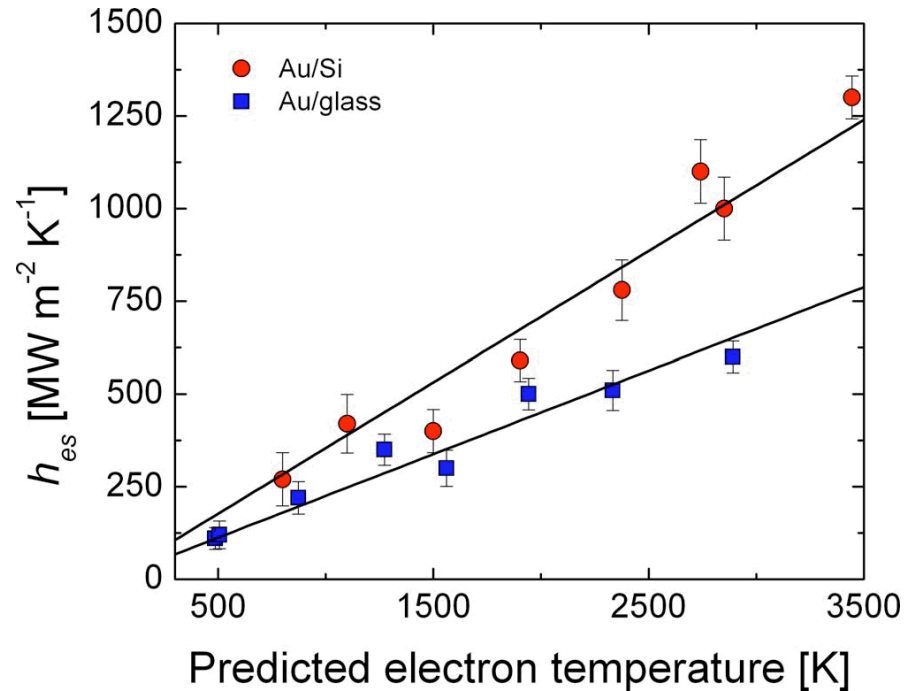
# Outline

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  - Thermal conductivity measurements of metalized layers
  - Electron-phonon coupling factor measurements in metal films
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  - Ballistic transport
  - Interface scattering

# Influence of electron-interface scattering on $G$



Film thickness and substrate dependence suggests electron-interface scattering.



Use 3 temperature model (3TM) to determine  $h_{es}$

# Influence of electron-interface scattering on thermoreflectance

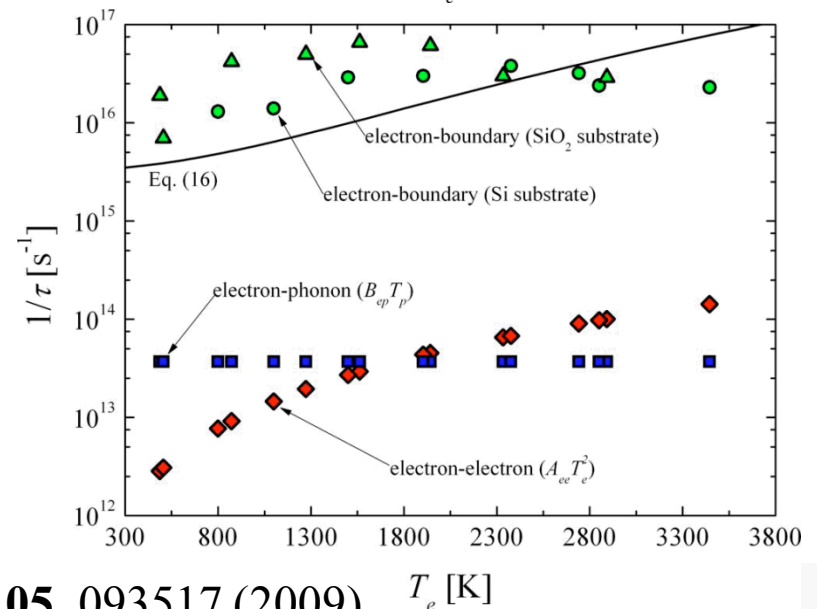
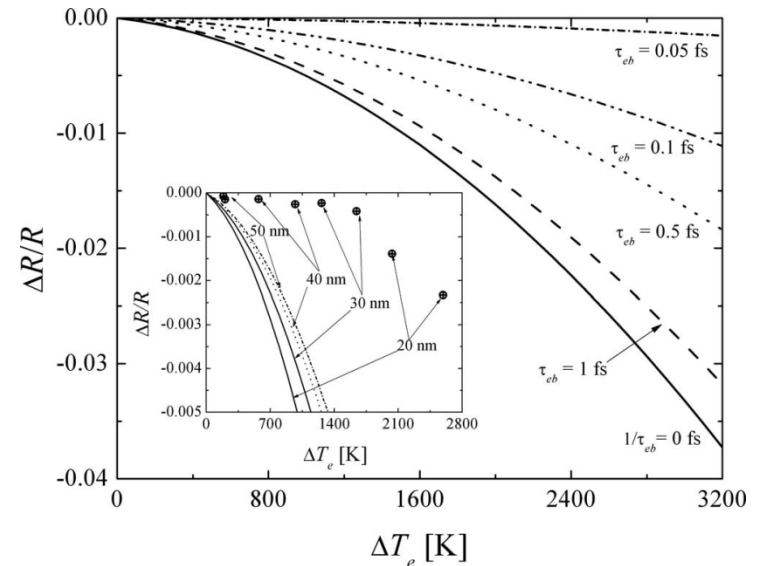
The thermoreflectance coefficient

Consider Drude model that accounts for electron-interface scattering

$$n = n_1 + in_2 = \sqrt{\epsilon_f} = \sqrt{1 - \frac{\omega_p^2}{\omega\left(\omega + \frac{i}{\tau}\right)}}$$

$$\frac{1}{\tau} = \frac{1}{\tau_{ee}} + \frac{1}{\tau_{ep}} + \frac{1}{\tau_{eb}}$$

$$\frac{1}{\tau_{eb}} = \frac{3\pi\left(\frac{1}{\tau_{ee}} + \frac{1}{\tau_{ep}}\right)^2}{35\zeta(3)q_{th}v_L} \left[ 1 + 2\left(\frac{v_L}{v_T}\right)^3 \right]$$



Hopkins, Journal of Applied Physics, **105**, 093517 (2009)



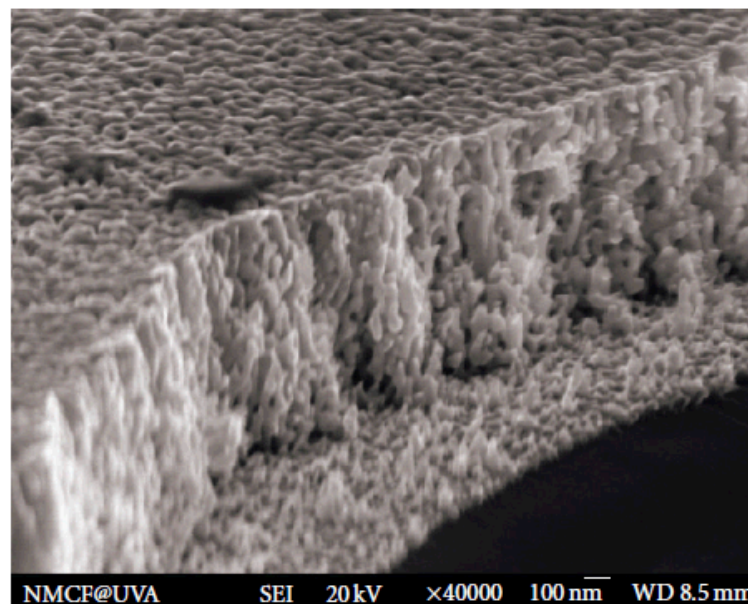
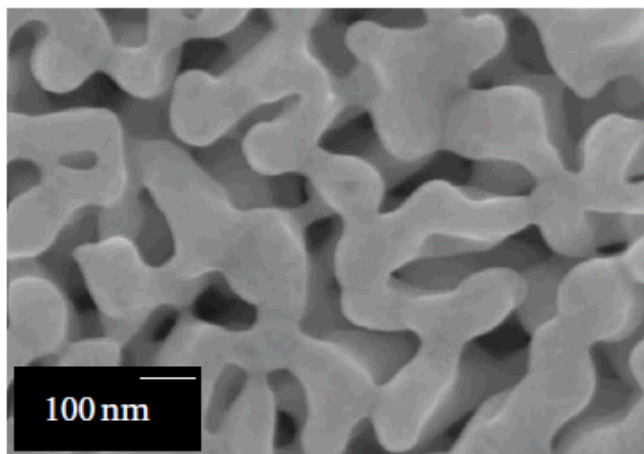
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# Thermal properties of nanoporous metals

“Matrix” of nanowires



Nanoporous  
Au layer

Adhesive  
Cr and Au layer

Si substrate

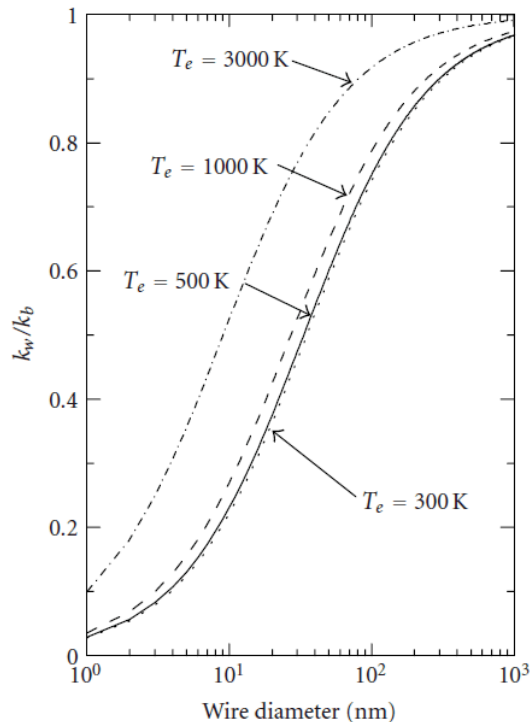
Thermal properties should show influence from ligament-boundary scattering

Hopkins *et al.*, Journal of Nanomaterials, **2008**, 418050 (2008)

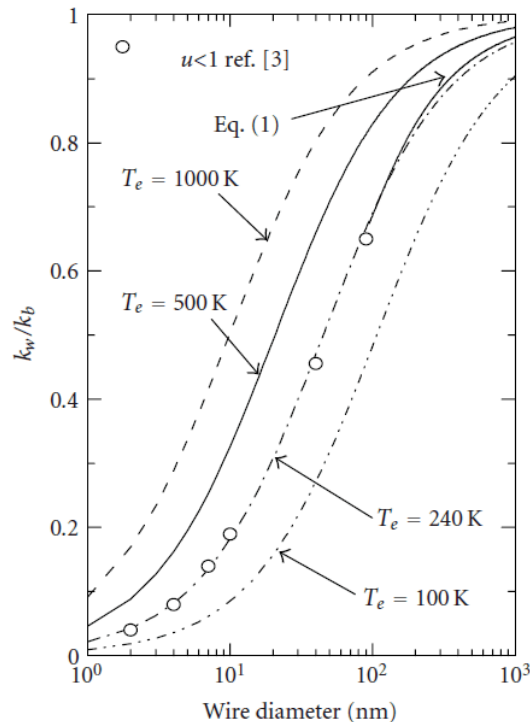
# Effect of electron-phonon nonequilibrium and boundary scattering on thermal conductivity

$$\Lambda = \frac{1}{3} C v \lambda = \frac{1}{3} C v^2 \tau$$

$\nearrow$  ep non-equilibrium  $\Lambda = \frac{1}{3} \gamma T_e v_F^2 \frac{1}{A T_e^2 + B T_p + \frac{v_F}{d}}$   
 $\searrow$  ep equilibrium  $\Lambda = \frac{1}{3} \gamma T v_F^2 \frac{1}{A T^2 + B T + \frac{v_F}{d}}$



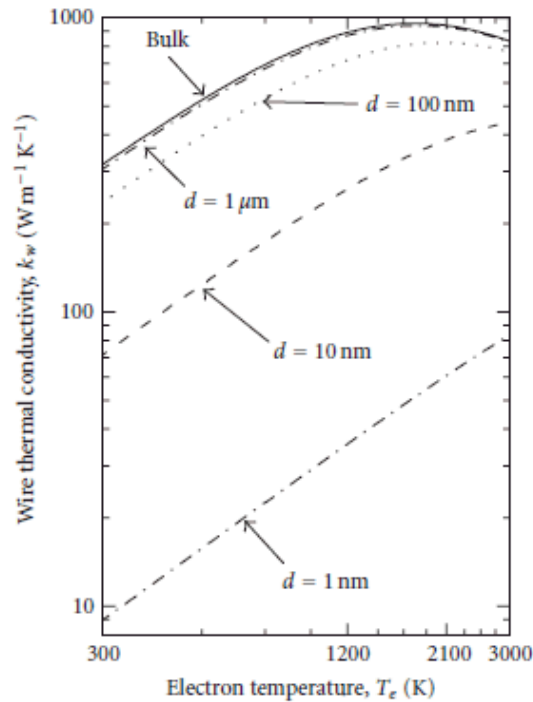
(a)



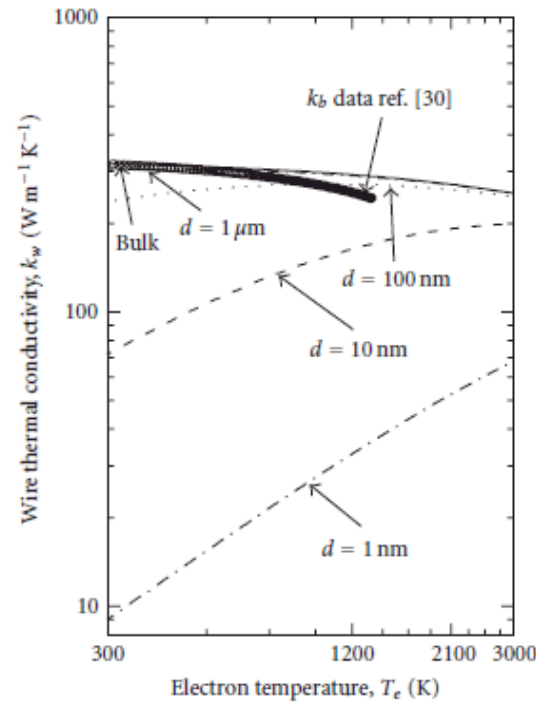
(b)

$$\frac{1}{\tau} = \frac{1}{\tau_{ee}} + \frac{1}{\tau_{ep}} + \frac{1}{\tau_{eb}}$$

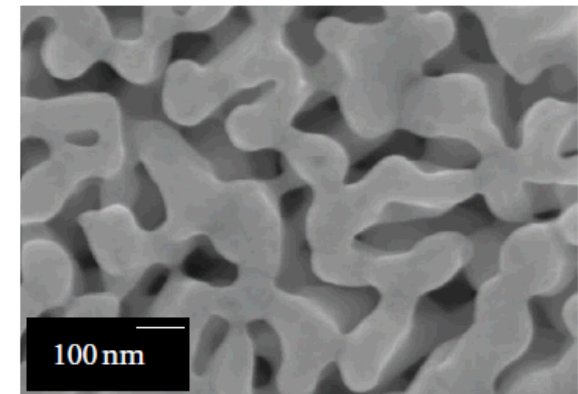
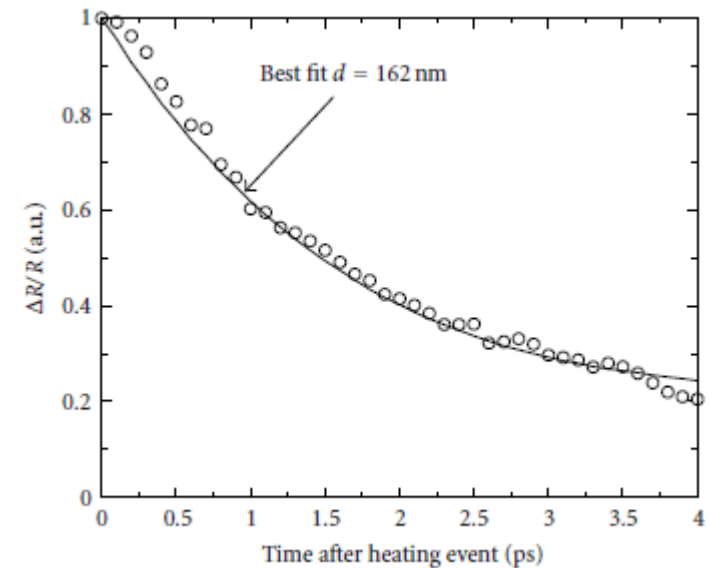
# Effect of electron-phonon nonequilibrium and boundary scattering on thermal conductivity



(a)



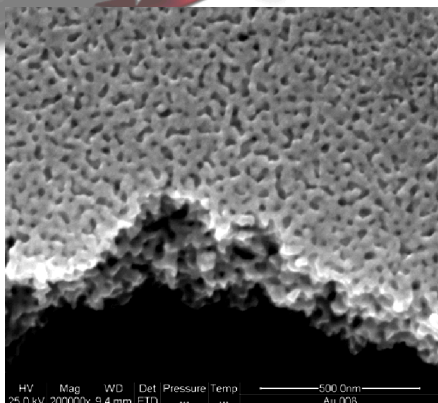
(b)



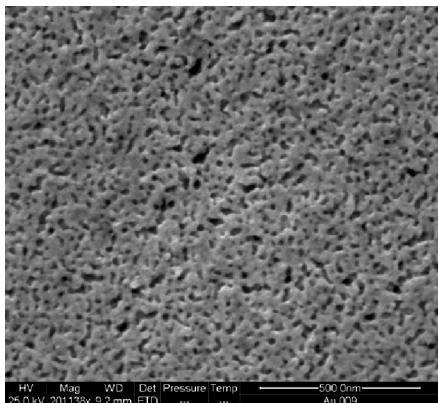
# G in nanoporous metals

Nanoporous metal fabrication at CINT

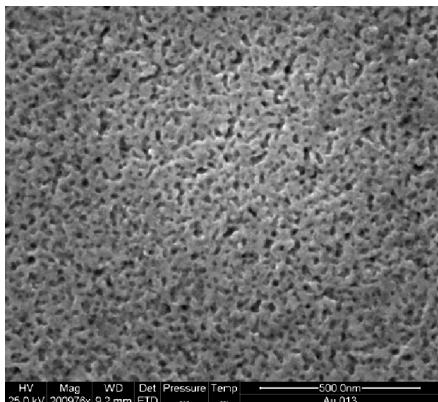
Collaborators: Amit Misra and Hongqi Li



Au-8



Au-9



Au-13

